

Global Fully Automatic Die Bonder Equipment Supply, Demand and Key Producers, 2023-2029

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Abstracts

The global Fully Automatic Die Bonder Equipment market size is expected to reach \$ million by 2029, rising at a market growth of % CAGR during the forecast period (2023-2029).

Fully-automated industrial versions are for large-scale mass production. Die bonders are specialized semi- or fully-automatic high-precision machine tools used in semiconductor device fabrications. Die bonders fix the semiconductor chip, or die, to the substrate, package, or lead frame, using an adhesive glue in a clean room environment, eutectic material or solder. Usually the chip or die is a 25 mm square and comes in wafer trays. Die bonding machines have to be accurate down to the micron level.

This report studies the global Fully Automatic Die Bonder Equipment production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Fully Automatic Die Bonder Equipment, and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2022 as the base year. This report explores demand trends and competition, as well as details the characteristics of Fully Automatic Die Bonder Equipment that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Fully Automatic Die Bonder Equipment total production and demand, 2018-2029, (K Units)

Global Fully Automatic Die Bonder Equipment total production value, 2018-2029, (USD

Million)

Global Fully Automatic Die Bonder Equipment production by region & country, production, value, CAGR, 2018-2029, (USD Million) & (K Units)

Global Fully Automatic Die Bonder Equipment consumption by region & country, CAGR, 2018-2029 & (K Units)

U.S. VS China: Fully Automatic Die Bonder Equipment domestic production, consumption, key domestic manufacturers and share

Global Fully Automatic Die Bonder Equipment production by manufacturer, production, price, value and market share 2018-2023, (USD Million) & (K Units)

Global Fully Automatic Die Bonder Equipment production by Type, production, value, CAGR, 2018-2029, (USD Million) & (K Units)

Global Fully Automatic Die Bonder Equipment production by Application production, value, CAGR, 2018-2029, (USD Million) & (K Units)

This reports profiles key players in the global Fully Automatic Die Bonder Equipment market based on the following parameters – company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Toray Engineering, FASFORD TECHNOLOGY, Besi, ASM Pacific Technology Limited (ASMPT), Kulicke & Soffa Industries Inc., Tresky AG, SHIBAURA MECHATRONICS CORPORATION, West Bond and Panasonic Corporation, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals, COVID-19 and Russia-Ukraine War Influence.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Fully Automatic Die Bonder Equipment market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (K Units) and average price (US\$/Unit) by manufacturer, by Type, and by Application. Data is given for the years 2018-2029 by

year with 2022 as the base year, 2023 as the estimate year, and 2024-2029 as the forecast year.

Global Fully Automatic Die Bonder Equipment Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Fully Automatic Die Bonder Equipment Market, Segmentation by Type

Epoxy Die Bonder

Eutectic Die Bonder

Soft Solder Die Bonder

Flip Chip Die Bonder

Global Fully Automatic Die Bonder Equipment Market, Segmentation by Application

Die Bonder Equipment for Integrated Device Manufacturers (DMs)

Die Bonder Equipment for Outsourced Semiconductor Assembly and Test (OSAT)

Companies Profiled:

Toray Engineering

FASFORD TECHNOLOGY

Besi

ASM Pacific Technology Limited (ASMPT)

Kulicke & Soffa Industries Inc.

Tresky AG

SHIBAURA MECHATRONICS CORPORATION

West Bond

Panasonic Corporation

MRSI Systems

SHINKAWA LTD.

Palomar Technologies

DIAS Automation

Key Questions Answered

1. How big is the global Fully Automatic Die Bonder Equipment market?
2. What is the demand of the global Fully Automatic Die Bonder Equipment market?
3. What is the year over year growth of the global Fully Automatic Die Bonder Equipment market?

4. What is the production and production value of the global Fully Automatic Die Bonder Equipment market?
5. Who are the key producers in the global Fully Automatic Die Bonder Equipment market?
6. What are the growth factors driving the market demand?

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